



WS2812B Functional characteristics

The 1204 ball interior integrates high-quality external single-line cascade IC and high-quality RGB LED chips, which are small in size and simple on the periphery.

BUILT-IN IC constant current high precision, internal RGB chip pre-optical processing

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Part No. :XL-3210RGB-WS2812E

Electrical operating parameters define the DC and AC parameters of a device within its operating range and under testing conditions that ensure specific performance indicators. For parameters without given upper and lower limits, this specification does not guarantee their accuracy, but their typical values

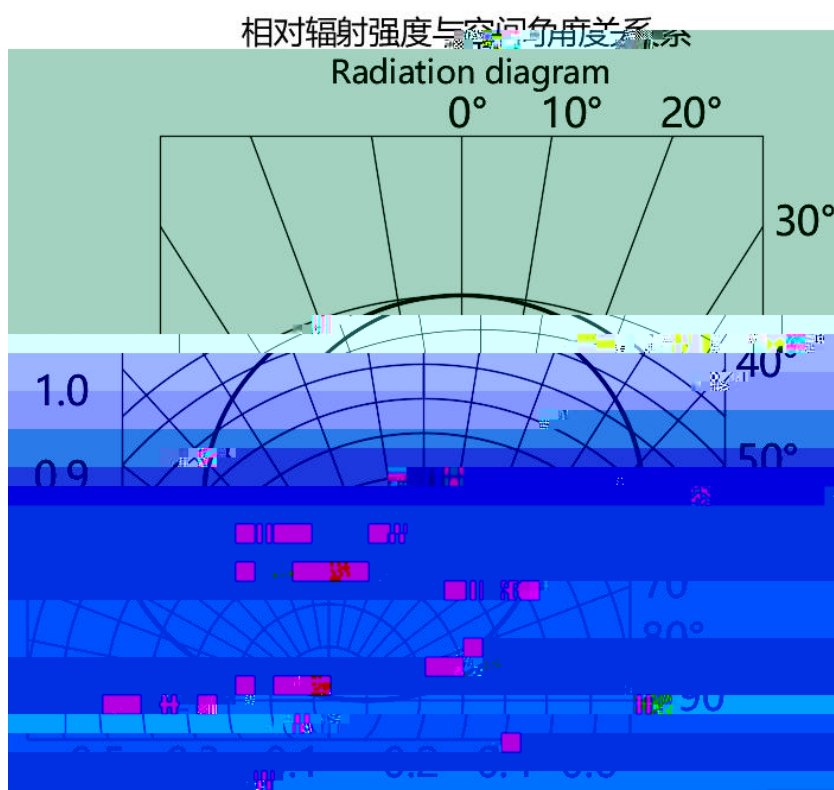
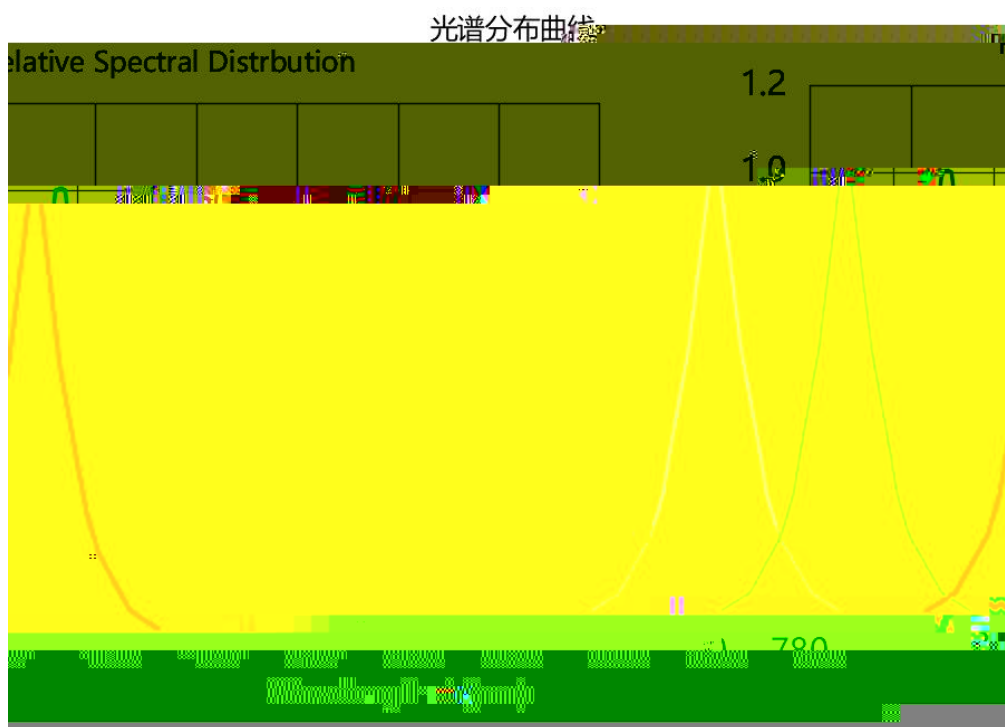






典型特性曲线

Typical Characteristics Curves



Part No. :XL-3210RGB-WS2812E



包装 (1)

Packaging (1)

载带与圆盘尺寸

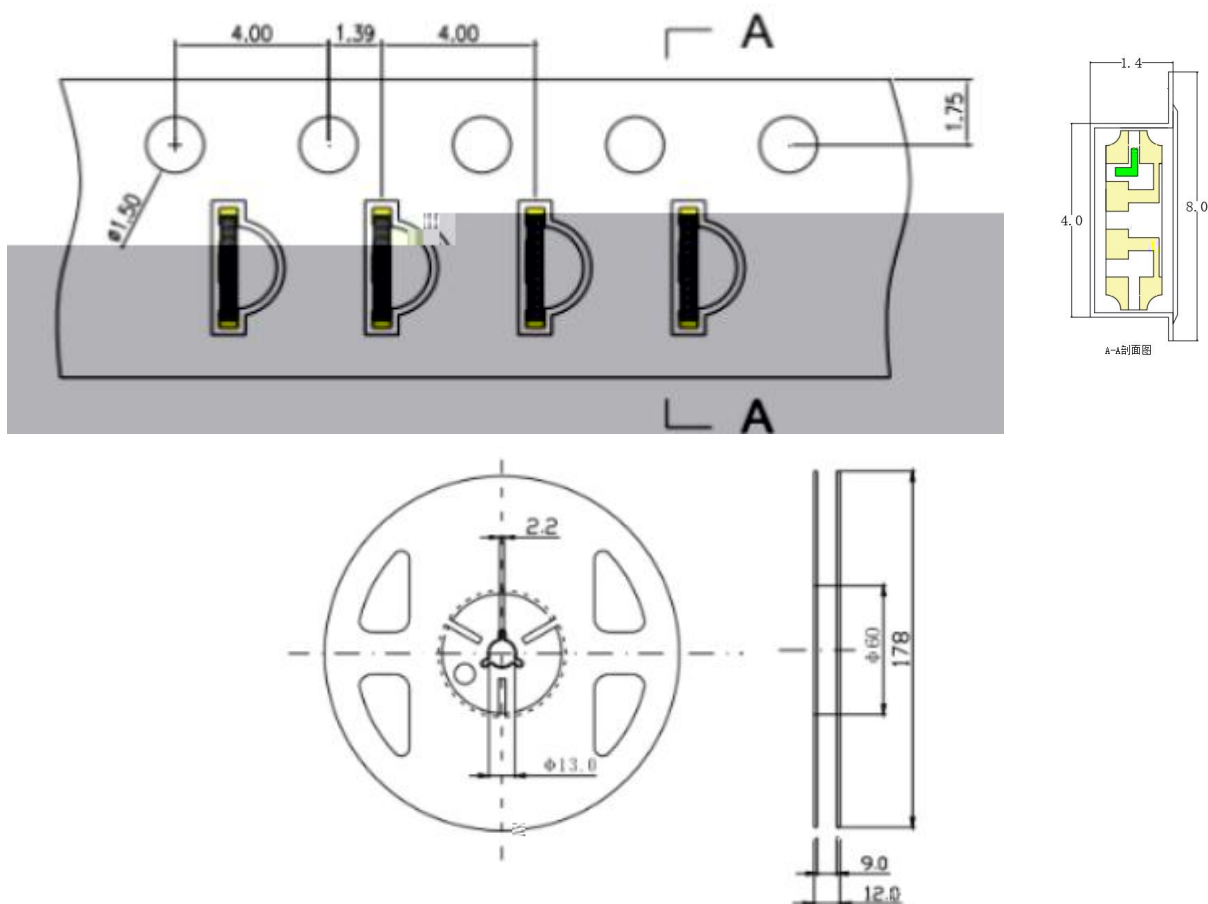


图 圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions

尾端

开始端

标签

载带卷出方向





Guideline for

烙铁入

W

300

3

LED

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the Soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is



焊接指导 (2)

Guideline for Soldering (2)

清洗:

30

30

3

50

LED

300W

LED

LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* 注意:

PCB

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base







